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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

: **Confirmation No. 9257**

Tetsuji TOGAWA et al.

: Attorney Docket No. 2005_0993A

Serial No. 10/539,245

: Group Art Unit 3723

Filed June 16, 2005

: Examiner Maurina T. Rachuba

SUBSTRATE HOLDING MECHANISM,
SUBSTRATE POLISHING APPARATUS
AND SUBSTRATE POLISHING METHOD

:

RESPONSE TO RESTRICTION REQUIREMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

This is in response to the Restriction Requirement of November 21, 2006.

Applicants, by their undersigned representative, hereby elect the invention of Group II, claims 2-8 and 34.

Having made the required election, a full examination on the merits of the elected invention is hereby requested.

Respectfully submitted,

Tetsuji TOGAWA et al.

By: Joseph M. Gorski

Joseph M. Gorski
Registration No. 46,500
Attorney for Applicants

JMG/nka
Washington, D.C. 20006-1021
Telephone (202) 721-8200
Facsimile (202) 721-8250
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FORM OF THIS PAPER TO DEPOSIT
IN THE UNIT NO. 23-0975